



Product Change Notification

Change Notification #: 116367 - 00
Change Title: Intel® 1U Riser3 Retimer Kit
A1U2PXR3HDAIC,
PCN 116367-00, Product Design,
Changing Rear Bracket design
Date of Publication: July 12, 2018

Key Characteristics of the Change:

Product Design

Forecasted Key Milestones:

Date Customer Must be Ready to Receive Post-Conversion Material: *	August 24, 2018
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* Intel appreciates the customer's desire to receive the latest revision of products. However, Intel manages inventory on a first in first out (FIFO) basis at the MM# level. Subsequently, customer requests for a specific revision of material (below the MM#) will not be supported by Intel.

Description of Change to the Customer:

Intel is changing the design of the rear bracket of the Intel® 1U PCIe Switch Riser 3 card kit "A1U2PXR3HDAIC". This new design improves the SFP+ Connectivity and rolls up the Top Assembly number (TA) as shown in the "table products affected".

Image 1. Bracket before the change

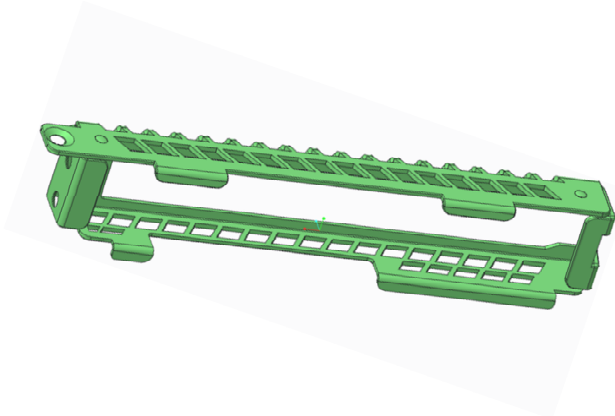
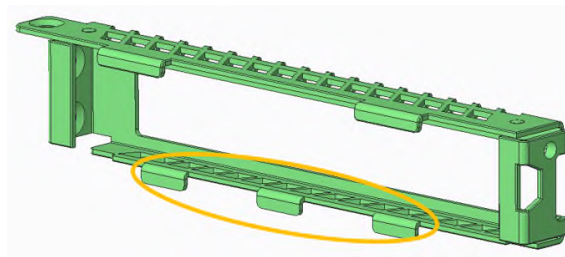


Image 2. Bracket after the change



Customer Impact of Change and Recommended Action:

Intel does not expect any impact to customers from this change, but encourages customers to understand the modification and determine the impact on their applications. For that reason Intel recommends that the customer perform a standard level of evaluation.

Please contact your local Intel Field Sales Rep if you have any further questions about these changes.

Products Affected / Intel Ordering Codes:

Product Code	MM#	Pre Change TA	Post Change TA
A1U2PXR3HDAIC	984450	H98267-002	H98267-003

PCN Revision History:

Date of Revision:

July 12, 2018

Revision Number:

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Reason:

Originally Published PCN



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Should you have any issues with the timeline or content of this change, please contact the Intel Representative(s) for your geographic location listed below. No response from customers will be deemed as acceptance of the change and the change will be implemented pursuant to the key milestones set forth in this attached PCN.

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